

**Single Phase, Isolated, AC Power Monitoring IC  
with Voltage Zero Crossing and Overcurrent Detection**

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## Not for New Design

The ACS71020 is in production but has been determined to be NOT FOR NEW DESIGN. This classification indicates that sale of this device is currently restricted to existing customer applications. The device should not be purchased for new design applications because obsolescence in the near future is probable. Samples are no longer available.

Date of status change: March 28, 2025

### Recommended Substitutions:

*For existing customer transition, and for new customers or new applications, refer to [ACS37800](#).*

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NOTE: For detailed information on purchasing options, contact your local Allegro field applications engineer or sales representative.

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## Single Phase, Isolated, AC Power Monitoring IC with Voltage Zero Crossing and Overcurrent Detection

### FEATURES AND BENEFITS

- Accurate power monitoring for AC applications
- UL certification for reinforced isolation up to 517 V<sub>RMS</sub> in a single package
- Accurate measurements of active, reactive, and apparent power, as well as power factor
- Separate rms and instantaneous measurements for both voltage and current channels
- 0.85 mΩ primary conductor resistance for low power loss and high inrush current withstand capability
- Dedicated voltage zero crossing pin
- Overcurrent fault output pin
- Hall-effect-based current measurement with common-mode stray field rejection
- User-programmable undervoltage and overvoltage thresholds for input voltage as well as overcurrent fault thresholds
- 1 kHz bandwidth
- Current sensing range from 0 to 90 A
- Options for I<sup>2</sup>C or SPI digital interface protocols
- User-programmable EEPROM and integrated charge pump
- 16-bit voltage and current ADCs

### PACKAGE

16-pin SOICW (suffix MA)



Not to scale

### DESCRIPTION

The Allegro ACS71020 power monitoring IC greatly simplifies the addition of power monitoring to many AC powered systems. The sensor may be powered from the same supply as the system's MCU, eliminating the need for multiple power supplies and expensive digital isolation ICs. The device's construction includes a copper conduction path that generates a magnetic field proportional to applied current. The magnetic field is sensed differentially to reject errors introduced by common mode fields.

Allegro's Hall-effect-based galvanically isolated current sensing technology achieves reinforced isolation ratings in a small PCB footprint. These features enable isolated current sensing without expensive Rogowski coils, oversized current transformers, isolated operational amplifiers, or the power loss of shunt resistors.

The ACS71020 power monitoring IC offers key power measurement parameters that can easily be accessed through its SPI or I<sup>2</sup>C digital protocol interfaces. Dedicated and configurable I/O pins for voltage zero crossing, undervoltage and overvoltage reporting, and overcurrent fault detection are also available (in I<sup>2</sup>C mode). The thresholds for overvoltage, undervoltage, and overcurrent are all user-programmable via EEPROM.

The ACS71020 is provided in a small low-profile surface mount SOIC16 wide-body package, is lead (Pb) free, and is fully calibrated prior to shipment from the Allegro factory. Customer calibration can further increase accuracy in application.



CB Certificate Number:  
US-32210-M1-UL

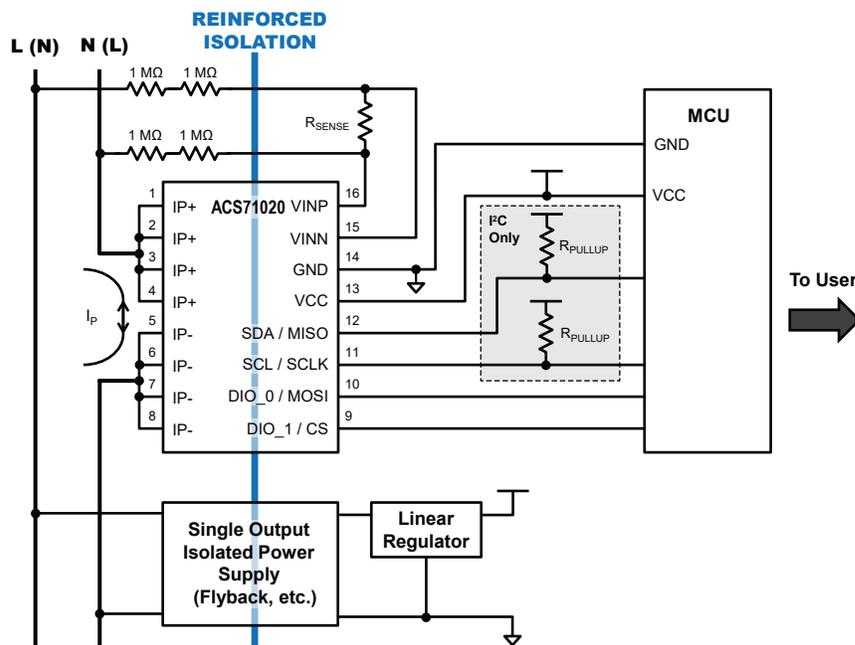


Figure 1: Typical Application

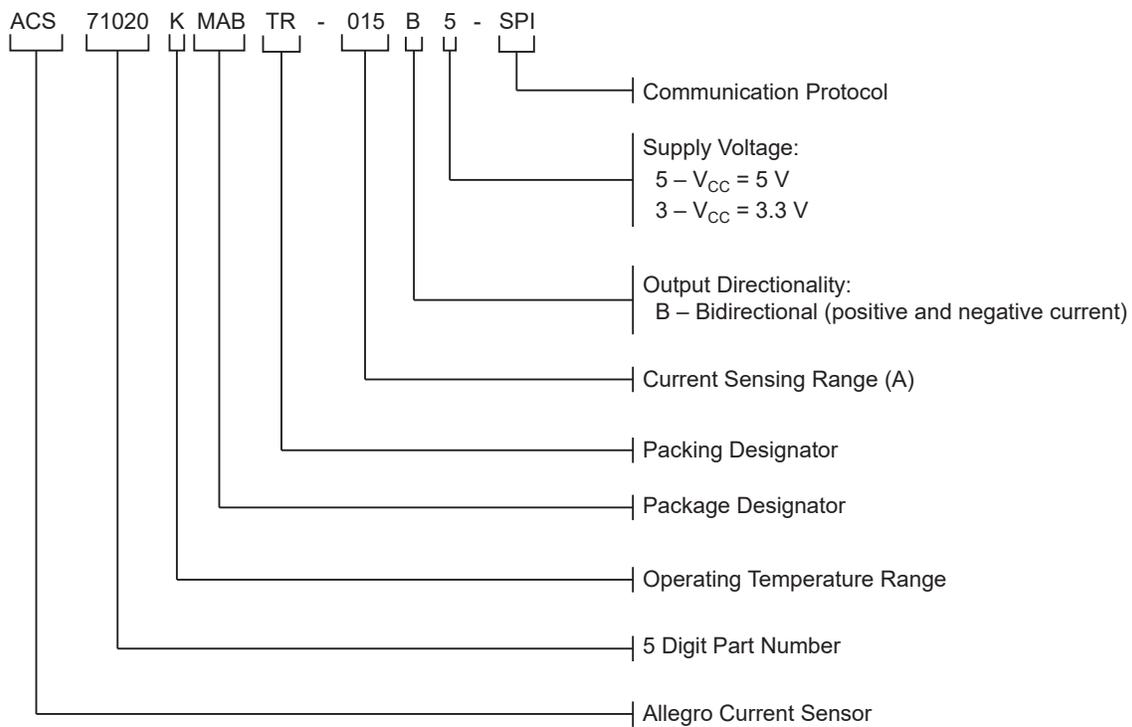
# ACS71020

## Single Phase, Isolated, AC Power Monitoring IC with Voltage Zero Crossing and Overcurrent Detection

### SELECTION GUIDE

Part Number	V <sub>CC(NOM)</sub> (V)	I <sub>PR</sub> (A)	Communication Protocol	T <sub>A</sub> (°C)	Packing [1]
ACS71020KMABTR-015B5-SPI	5	±15	SPI	-40 to 125	Tape and reel, 1000 pieces per reel, 3000 pieces per box
ACS71020KMABTR-030B3-SPI	3.3	±30			
ACS71020KMABTR-030B3-I2C	3.3	±30	I2C		
ACS71020KMABTR-090B3-I2C	3.3	±90			

[1] Contact Allegro for additional packing options.



### ABSOLUTE MAXIMUM RATINGS

Characteristic	Symbol	Notes	Rating	Units
Supply Voltage	$V_{CC}$		6.5	V
Reverse Supply Voltage	$V_{RCC}$		-0.5	V
Input Voltage	$V_{INP}$ , $V_{INN}$		$V_{CC} + 0.5$	V
Reverse Input Voltage	$V_{RNP}$ , $V_{RNN}$		-0.5	V
Digital I/O Voltage	$V_{DIO}$	SPI, I <sup>2</sup> C, and general purpose I/O	6	V
Reverse Digital I/O Voltage	$V_{RDIO}$		-0.5	V
Maximum Continuous Current	$I_{CMAX}$	$T_A = 25^\circ\text{C}$	60	A
Operating Ambient Temperature	$T_A$	Range K	-40 to 125	°C
Junction Temperature	$T_J(\text{max})$		165	°C
Storage Temperature	$T_{stg}$		-65 to 170	°C

### ISOLATION CHARACTERISTICS

Characteristic	Symbol	Notes	Rating	Unit
Dielectric Strength Test Voltage	$V_{ISO}$	Agency type-tested for 60 seconds per UL 60950-1 (edition 2). Production tested at 3000 $V_{RMS}$ for 1 second, in accordance with UL 60950-1 (edition 2).	4800	$V_{RMS}$
Working Voltage for Basic Isolation	$V_{WVBI}$	Maximum approved working voltage for basic (single) isolation according to UL 60950-1 (edition 2).	1480	$V_{PK}$ or VDC
			1047	$V_{RMS}$
Working Voltage for Reinforced Isolation	$V_{WVRI}$	Maximum approved working voltage for reinforced isolation according to UL 60950-1 (edition 2).	730	$V_{PK}$ or VDC
			517	$V_{RMS}$
Clearance	$D_{cl}$	Minimum distance through air from IP leads to signal leads.	7.5	mm
Creepage	$D_{cr}$	Minimum distance along package body from IP leads to signal leads	7.9	mm
Distance Through Insulation	DTI	Minimum internal distance through insulation	90	$\mu\text{m}$
Comparative Tracking Index	CTI	Material Group II	400 to 599	V

### ESD RATINGS

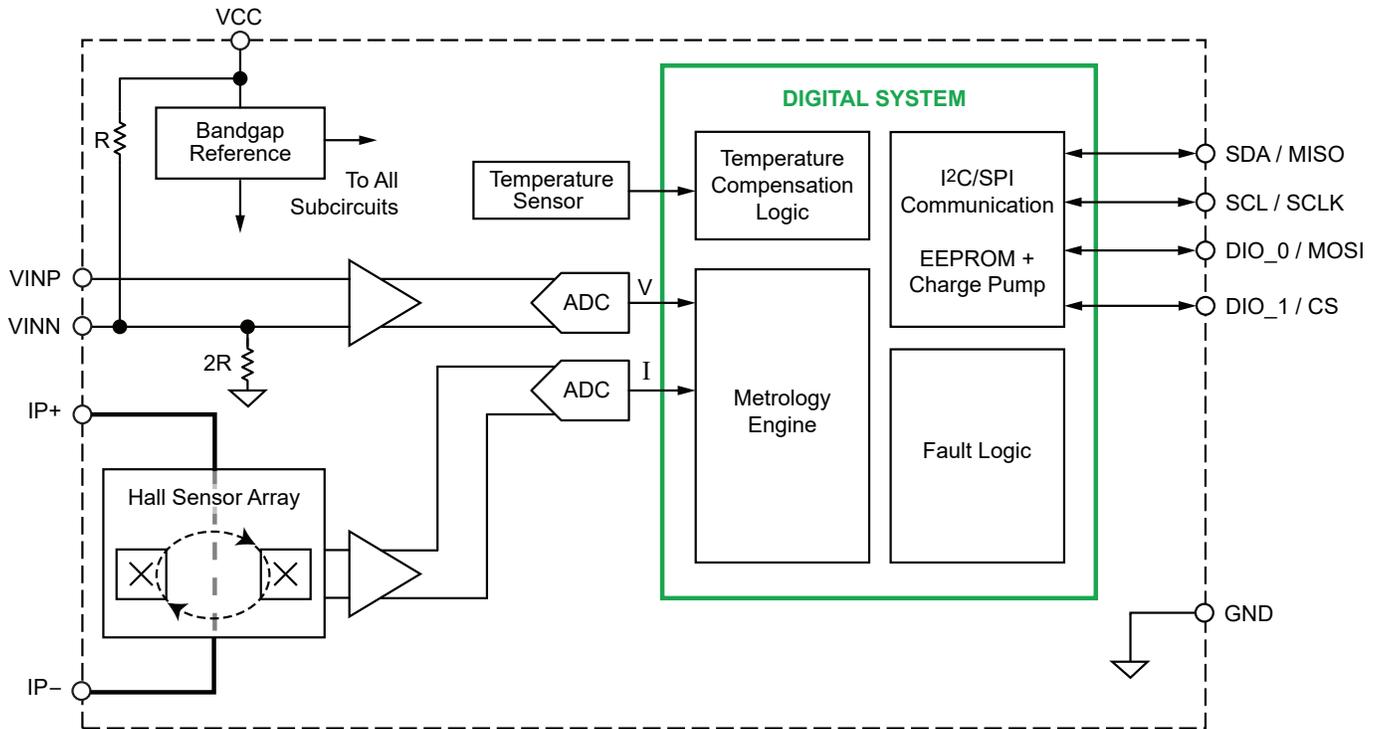
Characteristic	Symbol	Test Conditions	Value	Unit
Human Body Model	$V_{HBM}$	Per AEC-Q100	$\pm 4.5$	kV
Charged Device Model	$V_{CDM}$	Per AEC-Q100	$\pm 1$	kV

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Test Conditions*	Value	Units
Package Thermal Resistance (Junction to Ambient)	$R_{\theta JA}$	Mounted on the Allegro 85-0738 evaluation board with 700 mm <sup>2</sup> of 4 oz. copper on each side, connected to pins 1 and 2, and to pins 3 and 4, with thermal vias connecting the layers. Performance values include the power consumed by the PCB.	23	°C/W
Package Thermal Resistance (Junction to Lead)	$R_{\theta JL}$	Mounted on the Allegro ACS71020 evaluation board.	5	°C/W

\*Additional thermal information is available on the Allegro website. See <https://www.allegromicro.com/en/insights-and-innovations/technical-documents/hall-effect-sensor-ic-publications/dc-and-transient-current-capability-fuse-characteristics>.

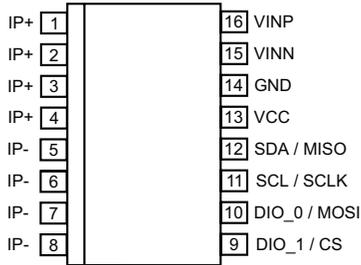
### FUNCTIONAL BLOCK DIAGRAM



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### PINOUT DIAGRAM AND TERMINAL LIST



Pinout Diagram

Terminal List Table

Number	Name	Description	
		I2C	SPI
1, 2, 3, 4	IP+	Terminals for current being sensed; fused internally	
5, 6, 7, 8	IP-	Terminals for current being sensed; fused internally	
9	DIO_1 / CS	Digital I/O 1	Chip Select (CS)
10	DIO_0 / MOSI	Digital I/O 0	MOSI
11	SCL / SCLK	SCL	SCLK
12	SDA / MISO	SDA	MISO
13	VCC	Device power supply terminal	
14	GND	Device Power and Signal ground terminal	
15	VINN	Negative Input Voltage	
16	VINP	Positive Input Voltage	

### DIGITAL I/O

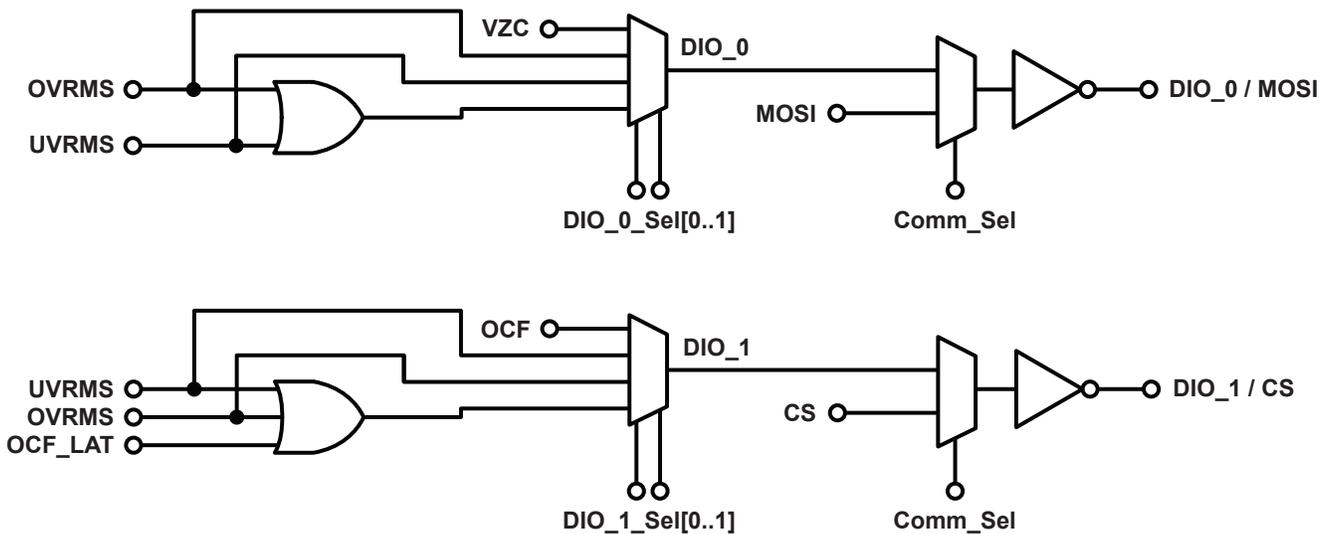
The Digital I/O can be programmed to represent the following functions (digital output pins are low true):

#### DIO\_0:

0. VZC: Voltage zero crossing
1. OVRMS: The VRMS overvoltage flag
2. UVRMS: The VRMS undervoltage flag
3. The OR of OVRMS and UVRMS (if either flag is triggered, the DIO\_0 pin will be asserted)

#### DIO\_1:

0. OCF: Overcurrent fault
1. UVRMS: The VRMS undervoltage flag
2. OVRMS: The VRMS overvoltage flag
3. The OR of OVRMS, UVRMS, and OCF\_LAT [latched overcurrent fault] (if any of the three flags are triggered, the DIO\_1 pin will be asserted)



**COMMON ELECTRICAL CHARACTERISTICS** [1]: Valid through the full range of  $T_A$  and  $V_{CC} = V_{CC(nom)}$ , unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>ELECTRICAL CHARACTERISTICS</b>						
Supply Voltage	$V_{CC}$		$V_{CC(nom)} \times 0.9$	$V_{CC(nom)}$	$V_{CC(nom)} \times 1.1$	V
Supply Current	$I_{CC}$	$V_{CC(min)} \leq V_{CC} \leq V_{CC(max)}$ , no load on output pins	–	12	14	mA
Power-On Time	$t_{PO}$		–	90	–	$\mu$ s
<b>VOLTAGE INPUT BUFFER</b>						
Differential Input Range	$\Delta V_{IN}$	$V_{INP} - V_{INN}$	–275	–	275	mV
Common Mode Input Voltage	$V_{IN(CM)}$		$\frac{2}{3} \times V_{CC} - 0.275$	–	$\frac{2}{3} \times V_{CC} + 0.275$	V
<b>VOLTAGE CHANNEL ADC</b>						
Sample Frequency	$f_S$		–	32	–	kHz
Number of Bits	$N_{ADC(V)}$		–	16	–	bits
Voltage ADC Power Supply Rejection	$V\_PSRR$	Ratio of change on $V_{CC}$ to change in ADC internal reference at DC	60	70	–	dB
<b>VOLTAGE CHANNEL</b>						
Noise	$V_N$		–	10	–	LSB
Internal Bandwidth	BW		–	1	–	kHz
Linearity Error	$E_{LIN}$		–	$\pm 0.2$	–	%
<b>CURRENT CHANNEL ADC</b>						
Sample Frequency	$f_S$		–	32	–	kHz
Number of Bits	$N_{ADC(I)}$		–	16	–	bits
Current Channel ADC Power Supply Rejection	$I\_PSRR$	Ratio of change on $V_{CC}$ to change in ADC internal reference at DC	60	70	–	dB
<b>CURRENT CHANNEL</b>						
Internal Bandwidth	BW		–	1	–	kHz
Primary Conductor Resistance	$R_{IP}$	$T_A = 25^\circ\text{C}$	–	0.85	–	m $\Omega$
Noise	$V_N$		–	100	–	LSB
Linearity Error	$E_{LIN}$		–	$\pm 1.5$	–	%
<b>OVERCURRENT FAULT CHARACTERISTICS</b>						
Fault Response Time	$t_{RF}$	Time from $I_P$ rising above $I_{FAULT}$ until $V_{FAULT} < V_{FAULT(max)}$ for a current step from 0 to $1.2 \times I_{FAULT}$ ; 10 k $\Omega$ and 100 pF from DIO_1 to ground; FLTDLY = 0	–	5	–	$\mu$ s
Internal Bandwidth	BW		–	200	–	kHz
Fault Hysteresis [2]	$I_{HYST}$		–	$0.05 \times I_{PR}$	–	A
Fault Range	$I_{FAULT}$	Set using FAULT field in EEPROM	$0.5 \times I_{PR}$	–	$1.75 \times I_{PR}$	A
<b>VOLTAGE ZERO CROSSING</b>						
Voltage Zero Crossing Delay	$t_d$		–	350	–	$\mu$ s

Continued on next page...

# ACS71020

## Single Phase, Isolated, AC Power Monitoring IC with Voltage Zero Crossing and Overcurrent Detection

**COMMON ELECTRICAL CHARACTERISTICS** <sup>[1]</sup> (continued): Valid through the full range of  $T_A$  and  $V_{CC} = V_{CC(nom)}$ , unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>DIO PINS</b>						
DIO Output High Level		$V_{CC} = 3.3\text{ V}$	3	–	–	V
DIO Output Low Level		$V_{CC} = 3.3\text{ V}$	–	–	0.3	V
DIO Input Voltage for Address Selection 0		$V_{CC} = 3.3\text{ V}$	–	0	–	V
DIO Input Voltage for Address Selection 1		$V_{CC} = 3.3\text{ V}$	–	1.1	–	V
DIO Input Voltage for Address Selection 2		$V_{CC} = 3.3\text{ V}$	–	2.2	–	V
DIO Input Voltage for Address Selection 3		$V_{CC} = 3.3\text{ V}$	–	3.3	–	V

<sup>[1]</sup> Device may be operated at higher primary current levels,  $I_P$ , ambient,  $T_A$ , and internal leadframe temperatures,  $T_A$ , provided that the maximum junction temperature,  $T_{j(max)}$ , is not exceeded.

<sup>[2]</sup> After  $I_P$  goes above  $I_{FAULT}$ , tripping the internal fault comparator,  $I_P$  must go below  $I_{FAULT} - I_{HYST}$ , before the internal fault comparator will reset.

**xKMATR-I2C OPERATING CHARACTERISTICS:** Valid through the full range of  $T_A$ ,  $V_{CC} = V_{CC(nom)}$ ,  $R_{EXT} = 10\text{ k}\Omega$ , unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>I<sup>2</sup>C INTERFACE CHARACTERISTICS [1]</b>						
Bus Free Time Between Stop and Start	$t_{BUF}$		1.3	–	–	$\mu\text{s}$
Hold Time Start Condition	$t_{hdSTA}$		0.6	–	–	$\mu\text{s}$
Setup Time for Repeated Start Condition	$t_{suSTA}$		0.6	–	–	$\mu\text{s}$
SCL Low Time	$t_{LOW}$		1.3	–	–	$\mu\text{s}$
SCL High Time	$t_{HIGH}$		0.6	–	–	$\mu\text{s}$
Data Setup Time	$t_{suDAT}$		100	–	–	$\mu\text{s}$
Data Hold Time	$t_{hdDAT}$		0	–	900	$\mu\text{s}$
Setup Time for Stop Condition	$t_{suSTO}$		0.6	–	–	$\mu\text{s}$
Logic Input Low Level (SDA, SCL pins)	$V_{IL}$		–	–	30	$\%V_{CC}$
Logic Input High Level (SDA, SCL pins)	$V_{IH}$		70	–	–	$\%V_{CC}$
Logic Input Current	$I_{IN}$	Input voltage on SDA or SCL = 0 V to $V_{CC}$	–1	–	1	$\mu\text{A}$
Output Low Voltage (SDA)	$V_{OL}$	SDA sinking = 1.5 mA	–	–	0.36	V
Clock Frequency (SCL pin)	$f_{CLK}$		–	–	400	kHz
Output Fall Time (SDA pin)	$t_f$	$R_{EXT} = 2.4\text{ k}\Omega$ , $C_B = 100\text{ pF}$	–	–	250	ns
I <sup>2</sup> C Pull-Up Resistance	$R_{EXT}$		2.4	10	–	k $\Omega$
Total Capacitive Load for Each of SDA and SCL Buses	$C_B$		–	–	20	pF

[1] These values are ratiometric to the supply voltage, I<sup>2</sup>C interface characteristics are ensured by design and not factory tested.

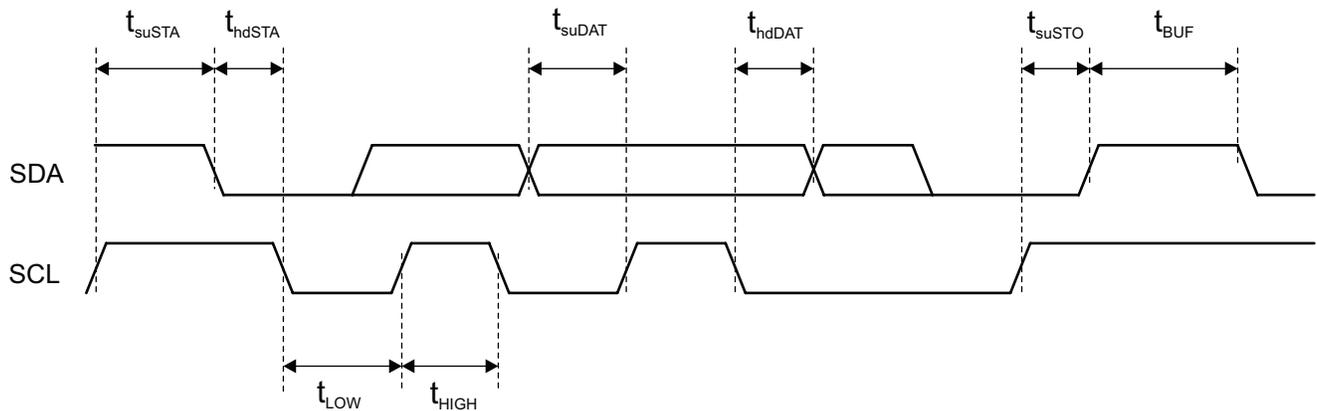


Figure 2: I<sup>2</sup>C Interface Timing

**xKMATR-SPI OPERATING CHARACTERISTICS [1]:** Valid through the full range of  $T_A$ ,  $V_{CC} = V_{CC(nom)}$ , unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>SPI INTERFACE CHARACTERISTICS</b>						
Digital Input High Voltage	$V_{IH}$	MOSI, SCLK, CS pins, $V_{CC} (nom) = 3.3 V$	2.8	–	3.63	V
		MOSI, SCLK, CS pins, $V_{CC} (nom) = 5 V$	4	–	5.5	V
Digital Input Low Voltage	$V_{IL}$	MOSI, SCLK, CS pins	–	–	0.5	V
SPI Output High Voltage	$V_{OH}$	MISO pin, $C_L = 20 pF$ , $T_A = 25^\circ C$ , $V_{CC} (nom) = 3.3 V$	2.8	3.3	3.8	V
		MISO pin, $C_L = 20 pF$ , $T_A = 25^\circ C$ , $V_{CC} (nom) = 5 V$	4	5	5.5	V
SPI Output Low Voltage	$V_{OL}$	MISO pin, $C_L = 20 pF$ , $T_A = 25^\circ C$	–	0.3	0.5	V
SPI Clock Frequency	$f_{SCLK}$	MISO pin, $C_L = 20 pF$	0.1	–	10	MHz
SPI Frame Rate	$t_{SPI}$		5.8	–	588	kHz
Chip Select to First SCLK Edge	$t_{CS}$	Time from CS going low to SCLK falling edge	50	–	–	ns
Data Output Valid Time	$t_{DAV}$	Data output valid after SCLK falling edge	–	40	–	ns
MOSI Setup Time	$t_{SU}$	Input setup time before SCLK rising edge	25	–	–	ns
MOSI Hold Time	$t_{HD}$	Input hold time after SCLK rising edge	50	–	–	ns
SCLK to CS Hold Time	$t_{CHD}$	Hold SCLK high time before CS rising edge	5	–	–	ns
Load Capacitance	$C_L$	Loading on digital output (MISO) pin	–	–	20	pF

[1] The ACS71020 MISO pin continues to drive the MISO line when CS goes high. This may prevent other devices from communicating properly. It is recommended that the ACS71020 be the only device on the SPI bus if using SPI communication.

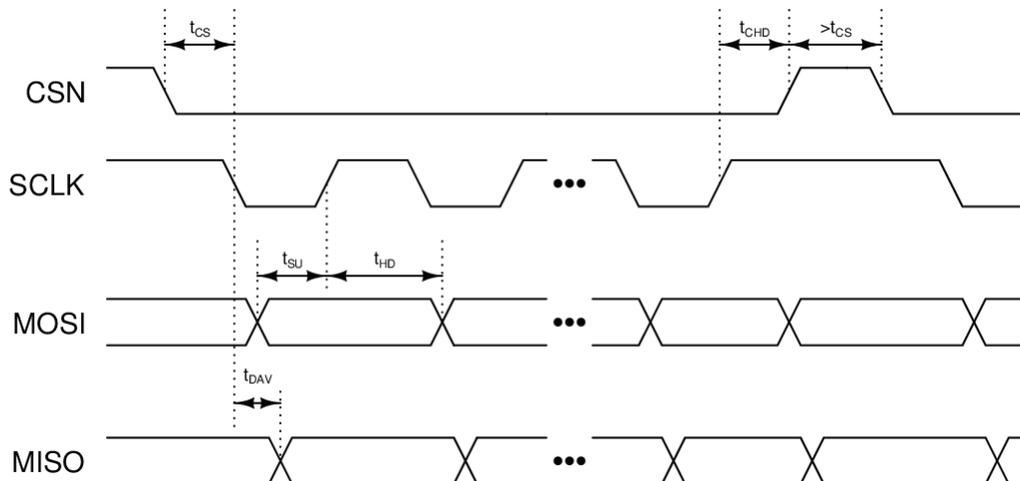


Figure 3: SPI Timing

# ACS71020

## Single Phase, Isolated, AC Power Monitoring IC with Voltage Zero Crossing and Overcurrent Detection

**ACS71020KMA-015B5 PERFORMANCE CHARACTERISTICS:** Valid through the full operating temperature range,  $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ ,  $C_{\text{BYPASS}} = 0.1 \mu\text{F}$ , and  $V_{\text{CC}} = 5 \text{ V}$ , unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Typ. [1]	Max.	Unit
<b>GENERAL CHARACTERISTICS</b>						
Nominal Supply Voltage	$V_{\text{CC}}(\text{nom})$		–	5	–	V
<b>NOMINAL PERFORMANCE – CURRENT CHANNEL</b>						
Current Sensing Range	$I_{\text{PR}}$		–15	–	15	A
Sensitivity	$\text{Sens}_{(I)}$	$I_{\text{PR}}(\text{min}) < I_P < I_{\text{PR}}(\text{max})$	–	2184	–	LSB/A
<b>ACCURACY PERFORMANCE – CURRENT CHANNEL</b>						
Total Output Error	$E_{\text{TOT}(I)}$	Measured at $I_P = I_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 2$	–	%
		Measured at $I_P = I_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 3$	–	%
<b>TOTAL OUTPUT ERROR COMPONENTS – CURRENT CHANNEL</b>						
Sensitivity Error	$E_{\text{SENS}(I)}$	Measured at $I_P = I_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 1$	–	%
		Measured at $I_P = I_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 1.5$	–	%
Offset Error	$E_{\text{O}(I)}$	$I_P = 0 \text{ A}$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 300$	–	LSB
		$I_P = 0 \text{ A}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 500$	–	LSB
<b>NOMINAL PERFORMANCE – VOLTAGE CHANNEL</b>						
Sensitivity	$\text{Sens}_{(V)}$	$V_{\text{PR}}(\text{min}) < V_P < V_{\text{PR}}(\text{max})$	–	238	–	LSB/mV
<b>ACCURACY PERFORMANCE – VOLTAGE CHANNEL</b>						
Total Output Error	$E_{\text{TOT}(V)}$	Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 1.2$	–	%
		Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 1.3$	–	%
<b>TOTAL OUTPUT ERROR COMPONENTS – VOLTAGE CHANNEL</b>						
Sensitivity Error	$E_{\text{SENS}(V)}$	Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 1$	–	%
		Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 1$	–	%
Offset Error	$E_{\text{O}(V)}$	$V_P = 0 \text{ mV}$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 100$	–	LSB
		$V_P = 0 \text{ mV}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 150$	–	LSB
<b>ACCURACY PERFORMANCE – ACTIVE POWER</b>						
Total Output Error	$E_{\text{TOT}(P)}$	Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 2.3$	–	%
		Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 3.3$	–	%

[1] Typical values are based on mean  $\pm 3$  sigma.

# ACS71020

## Single Phase, Isolated, AC Power Monitoring IC with Voltage Zero Crossing and Overcurrent Detection

**ACS71020KMA-030B3 PERFORMANCE CHARACTERISTICS:** Valid through the full operating temperature range,  $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ ,  $C_{\text{BYPASS}} = 0.1 \mu\text{F}$ , and  $V_{\text{CC}} = 3.3 \text{ V}$ , unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Typ. [1]	Max.	Unit
<b>GENERAL CHARACTERISTICS</b>						
Nominal Supply Voltage	$V_{\text{CC}}(\text{nom})$		–	3.3	–	V
<b>NOMINAL PERFORMANCE – CURRENT CHANNEL</b>						
Current Sensing Range	$I_{\text{PR}}$		–30	–	30	A
Sensitivity	$\text{Sens}_{(I)}$	$I_{\text{PR}}(\text{min}) < I_P < I_{\text{PR}}(\text{max})$	–	1092	–	LSB/A
<b>ACCURACY PERFORMANCE – CURRENT CHANNEL</b>						
Total Output Error	$E_{\text{TOT}(I)}$	Measured at $I_P = I_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 2$	–	%
		Measured at $I_P = I_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 3$	–	%
<b>TOTAL OUTPUT ERROR COMPONENTS – CURRENT CHANNEL</b>						
Sensitivity Error	$E_{\text{SENS}(I)}$	Measured at $I_P = I_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 1$	–	%
		Measured at $I_P = I_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 1.5$	–	%
Offset Error	$E_{\text{O}(I)}$	$I_P = 0 \text{ A}$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 500$	–	LSB
		$I_P = 0 \text{ A}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 700$	–	LSB
<b>NOMINAL PERFORMANCE – VOLTAGE CHANNEL</b>						
Sensitivity	$\text{Sens}_{(V)}$	$V_{\text{PR}}(\text{min}) < V_P < V_{\text{PR}}(\text{max})$	–	238	–	LSB/mV
<b>ACCURACY PERFORMANCE – VOLTAGE CHANNEL</b>						
Total Output Error	$E_{\text{TOT}(V)}$	Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 1.2$	–	%
		Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 1.3$	–	%
<b>TOTAL OUTPUT ERROR COMPONENTS – VOLTAGE CHANNEL</b>						
Sensitivity Error	$E_{\text{SENS}(V)}$	Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 1$	–	%
		Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 1$	–	%
Offset Error	$E_{\text{O}(V)}$	$V_P = 0 \text{ mV}$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 60$	–	LSB
		$V_P = 0 \text{ mV}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 80$	–	LSB
<b>ACCURACY PERFORMANCE – ACTIVE POWER</b>						
Total Output Error	$E_{\text{TOT}(P)}$	Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 2.3$	–	%
		Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 3.3$	–	%

[1] Typical values are based on mean  $\pm 3$  sigma.

**ACS71020KMA-090B3 PERFORMANCE CHARACTERISTICS:** Valid through the full operating temperature range,  $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ ,  $C_{\text{BYPASS}} = 0.1 \mu\text{F}$ , and  $V_{\text{CC}} = 3.3 \text{ V}$ , unless otherwise specified

Characteristic	Symbol	Test Conditions	Min.	Typ. [1]	Max.	Unit
<b>GENERAL CHARACTERISTICS</b>						
Nominal Supply Voltage	$V_{\text{CC}}(\text{nom})$		–	3.3	–	V
<b>NOMINAL PERFORMANCE – CURRENT CHANNEL</b>						
Current Sensing Range	$I_{\text{PR}}$		–90	–	90	A
Sensitivity	$\text{Sens}_{(I)}$	$I_{\text{PR}}(\text{min}) < I_P < I_{\text{PR}}(\text{max})$	–	364	–	LSB/A
<b>ACCURACY PERFORMANCE – CURRENT CHANNEL</b>						
Total Output Error	$E_{\text{TOT}(I)}$	Measured at $I_P = I_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 2$	–	%
		Measured at $I_P = I_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 3$	–	%
<b>TOTAL OUTPUT ERROR COMPONENTS – CURRENT CHANNEL</b>						
Sensitivity Error	$E_{\text{SENS}(I)}$	Measured at $I_P = I_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 1$	–	%
		Measured at $I_P = I_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 1.5$	–	%
Offset Error	$E_{\text{O}(I)}$	$I_P = 0 \text{ A}$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 300$	–	LSB
		$I_P = 0 \text{ A}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 500$	–	LSB
<b>NOMINAL PERFORMANCE – VOLTAGE CHANNEL</b>						
Sensitivity	$\text{Sens}_{(V)}$	$V_{\text{PR}}(\text{min}) < V_P < V_{\text{PR}}(\text{max})$	–	238	–	LSB/mV
<b>ACCURACY PERFORMANCE – VOLTAGE CHANNEL</b>						
Total Output Error	$E_{\text{TOT}(V)}$	Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 1.2$	–	%
		Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 1.3$	–	%
<b>TOTAL OUTPUT ERROR COMPONENTS – VOLTAGE CHANNEL</b>						
Sensitivity Error	$E_{\text{SENS}(V)}$	Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 1$	–	%
		Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 1$	–	%
Offset Error	$E_{\text{O}(V)}$	$V_P = 0 \text{ mV}$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 100$	–	LSB
		$V_P = 0 \text{ mV}$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 150$	–	LSB
<b>ACCURACY PERFORMANCE – ACTIVE POWER</b>						
Total Output Error	$E_{\text{TOT}(P)}$	Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = 25^\circ\text{C}$ to $125^\circ\text{C}$	–	$\pm 2.3$	–	%
		Measured at $V_P = V_{\text{PR}}(\text{max})$ , $T_A = -40^\circ\text{C}$ to $25^\circ\text{C}$	–	$\pm 3.3$	–	%

[1] Typical values are based on mean  $\pm 3$  sigma.

### DATA ACQUISITION

#### ADCs

Both the current and voltage channels are sampled at a high frequency and then digitally filtered and decimated to avoid large anti-aliasing filters. The final sample rate will be near 32 kHz for an 8 MHz clock. The digital low-pass filters have a cutoff of 1 kHz. The digital word from the ADC is 16 bits for both the current and the voltage.

#### Raw Signal Sensitivity and Offset Trim

The gain and offset for both current and voltage channels use a shared temperature compensation engine which is trimmed in production. The fine sensitivity and offset are also trimmed in production at the factory; however, the user has access to the fine sensitivity field for the current channel should they want to trim the gain in application.

#### Phase Compensation

Phase delay may be introduced on either the voltage or current channels. The range is EEPROM selectable, either 5° of delay (step size of 0.67°) or 40° of delay (step size of 5.36°).

#### Zero Crossing

The zero crossings are only detected on the voltage signal. Both the high-to-low and low-to-high transitions will be detected with time-based hysteresis that removes the possibility of noise causing multiple zero crossings to be reported at each true zero crossing.

The zero-crossing output can be a square wave that transitions at each zero crossing or a pulse with a fixed width at each zero crossing. When in pulse mode, the width of the pulse is  $t_p$  (see DELAYCNT\_SEL; nominal setting is 32  $\mu$ s). There will be a fixed delay,  $t_D$ , from the time that a true zero crossing has occurred to the time that it is reported. This delay helps to keep the zero-crossing detection more precise.

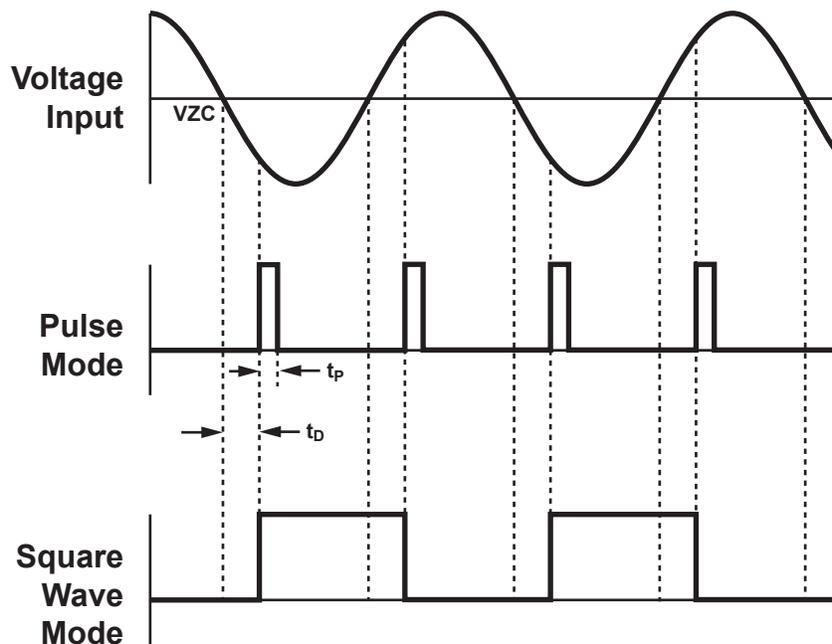


Figure 4: Zero Crossing

## POWER CALCULATIONS

### $I_{RMS} / V_{RMS}$

Half cycle-by-cycle calculation of the root mean square of both the current and voltage channels:

$$I_{RMS} = \sqrt{\frac{\sum_{n=0}^{n=N-1} I_n^2}{N}} \quad V_{RMS} = \sqrt{\frac{\sum_{n=0}^{n=N-1} V_n^2}{N}}$$

where  $I_n$  (Icodes) and  $V_n$  (Vcodes) are the instantaneous measurements of current and voltage, respectively. The figure below represents how the calculation is performed. Each voltage zero crossing determines end of the rms calculation window and also starts the next rms calculation window.

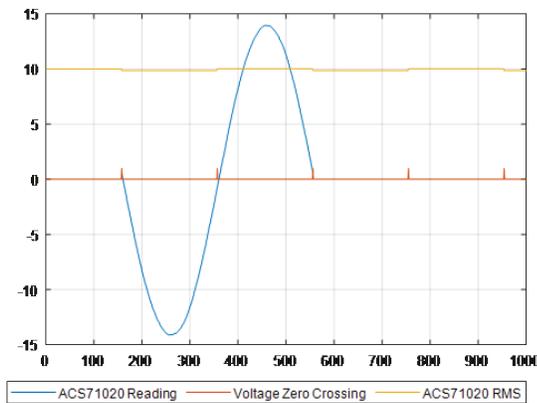


Figure 5

### Apparent Power

The magnitude of the complex power being measured; calculated at the end of each cycle:

$$|S| = I_{RMS} \times V_{RMS}$$

### Active Power

The real component of power being measured; calculated cycle by cycle:

$$P_{ACTIVE} = \frac{\sum_{n=0}^{n=N-1} P_n}{N} \quad P_n = I_n \times V_n$$

### Reactive Power

Imaginary component of power being measured; calculated at the end of each cycle:

$$Q = \sqrt{S^2 - P_{ACTIVE}^2}$$

### Power Factor

The magnitude of the ratio of real power to apparent power; calculated at the end of each cycle:

$$|PF| = \frac{P_{ACTIVE}}{|S|}$$

### Lead/Lag

The voltage leading or lagging the current will be communicated as a single bit. This bit also represents the sign of the reactive power. This is stored in the register field POSANGLE.

Leading or lagging is determined by comparing the zero crossings of the voltage and current channels.

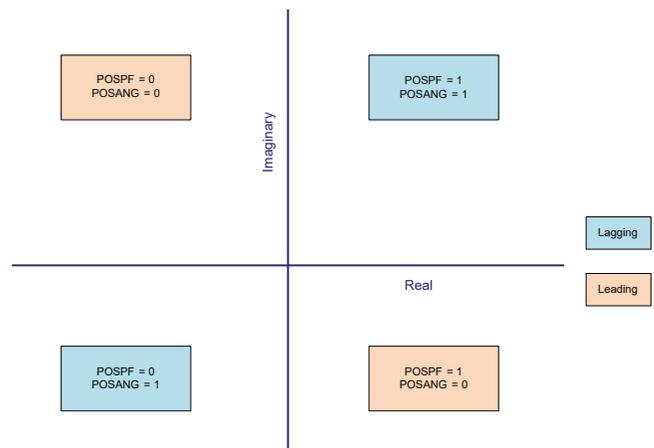


Figure 6

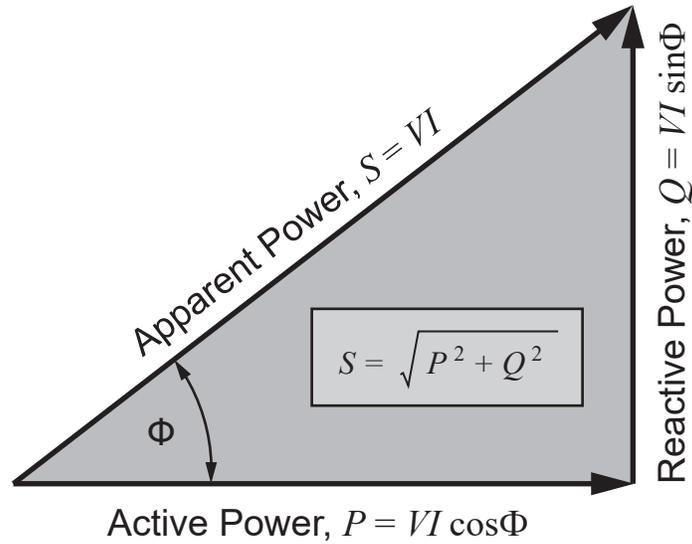


Figure 7: Power Triangle

## Overcurrent Fault

The overcurrent fault threshold may be set from 50% to 175% of  $I_p$ . The user sets the trip point with an 8-bit word. The user also has the ability to set the trip level digital delay. This allows for up to a 32  $\mu$ s delay on the fault.

## Averaging Over Time

IRMS or VRMS and PACTIVE may be averaged over a programmable number of updates. Note that either VMRS or IRMS can be averaged, not both.

The number of averages is controlled by two different registers. There is an accumulator that averages the above values. A 7-bit number, RMS\_AVG\_1, is used to determine the number of

averages. There is an additional accumulator that will be used to average the output of the first accumulator. There is a 10-bit number, RMS\_AVG\_2, that will be used to determine the number of averages for this accumulator. For optimal performance, setting an even number of averages for both accumulators is recommended. The combination of the two accumulators allows the user to select how long to average for as well as how often the values are updated. The exact time this averages over depends on n (the number of samples per cycle). Averages could be read in Reg 0x26 to 0x29.

## Over/Undervoltage Detection

There are two flags that can be used to detect undervoltage and overvoltage. These flags have a programmable voltage trip level. Refer to the Digital I/O section for all possible configurations.

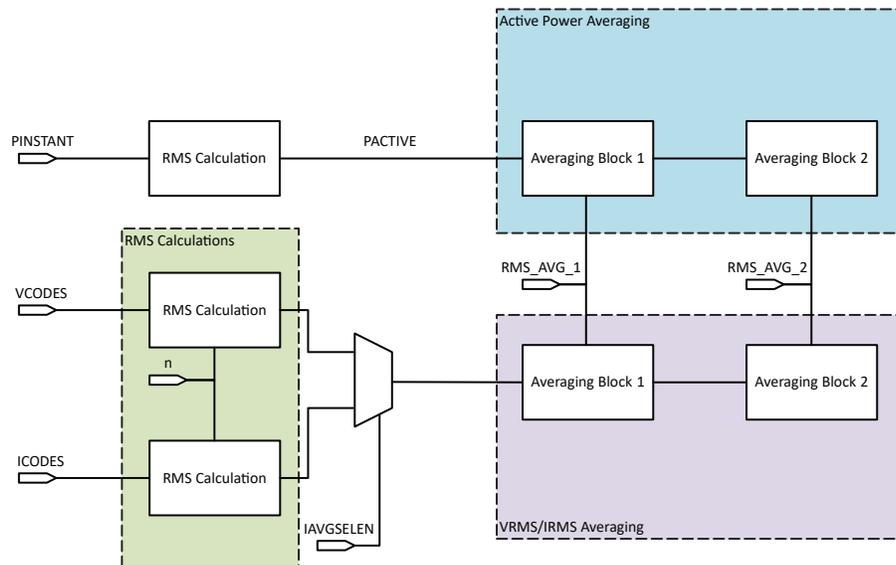


Figure 8: ACS71020 Trim Diagram

## DIGITAL COMMUNICATION

### Communication Interfaces

The ACS71020 supports communication over 1 MHz I<sup>2</sup>C and 10 MHz SPI. However, the communication protocol is fixed during factory programming. Refer to the Selection Guide for more information. The ACS71020 MISO pin continues to drive the MISO line when CS goes high. This may prevent other devices from communicating properly. It is recommended that the ACS71020 be the only device on the SPI bus if using SPI communication.

### SPI

The SPI frame consists of:

- The controller writes on the MOSI line the 7-bit address of the register to be read from or written to.
- The next bit on the MOSI line is the read/write (RW) indicator. A high state indicates a Read and a low state indicates a Write.
- The device sends a 32-bit response on the MISO line. The contents correspond to the previous command.
- On the MOSI line, if the current command is a write, the 32 bits correspond to the Write data, and in the case of a read, the data is ignored.

### Registers and EEPROM

#### WRITE ACCESS

The ACS71020 supports factory and customer EEPROM space as well as volatile registers. The customer access code must be sent prior to writing these customer EEPROM spaces. In addition, the device includes a set of free space EEPROM registers that are accessible with or without writing the access code.

#### READ ACCESS

All EEPROM and volatile registers may be read at any time regardless of the access code.

#### EEPROM

At power up, all shadow registers are loaded from EEPROM including all configuration parameters. The shadow registers can be written to in order to change the device behavior without having to perform an EEPROM write. Any changes made in shadow memory are volatile and do not persist through a reset event.

#### WRITING

The timing diagram for an EEPROM write is shown in Figure 9 and Figure 10.

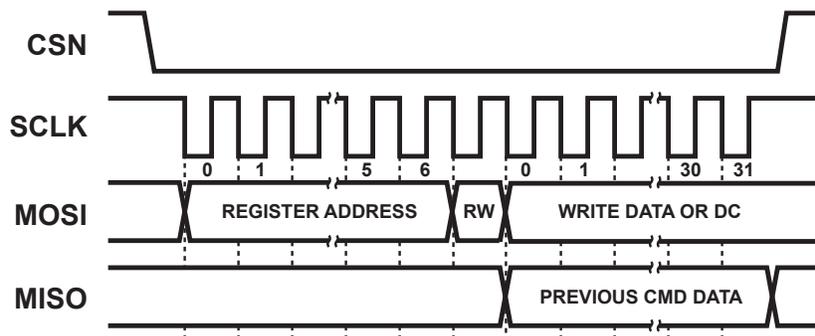


Figure 9: EEPROM Write – SPI Mode

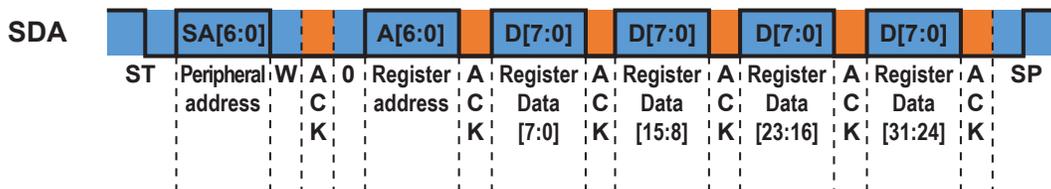
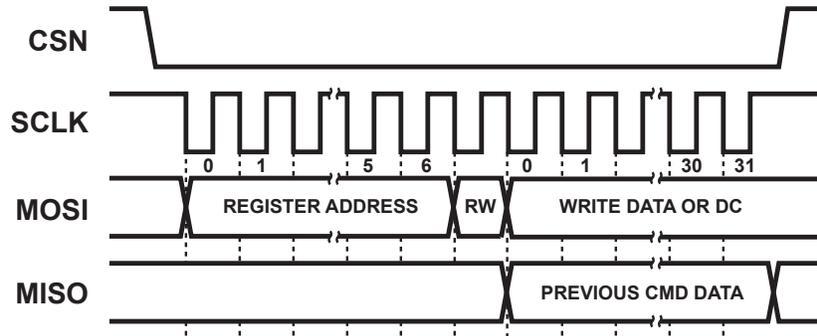


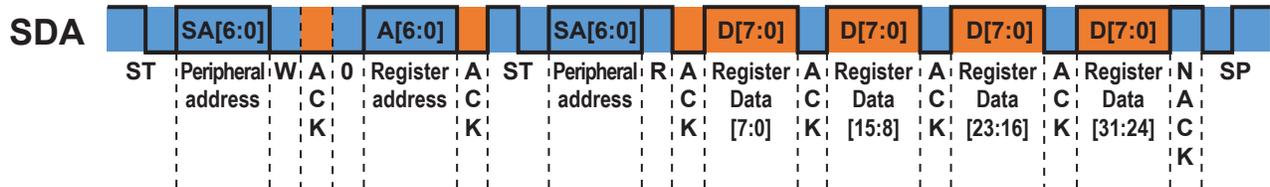
Figure 10: EEPROM Write – I<sup>2</sup>C Mode  
Blue represents data sent by the controller and orange is the data sent by the peripheral.

### READING

The timing diagram for an EEPROM read is shown in Figure 11 and Figure 12.



**Figure 11: EEPROM Read – SPI Mode**  
For SPI, the read data will be sent out during the above command.



**Figure 12: EEPROM Read – I<sup>2</sup>C Mode**  
Blue represents data sent by the controller and orange is the data sent by the peripheral.

### EEPROM Error Checking and Correction (ECC)

Hamming code methodology is implemented for EEPROM checking and correction (ECC). ECC is enabled after power-up.

The ACS71020 analyzes message data sent by the controller and the ECC bits are added. The first 6 bits sent from the device to the controller are dedicated to ECC. The device always returns 32 bits.

#### EEPROM ECC Errors

Bits	Name	Description
31:28	–	No meaning
27:26	ECC	00 = No Error 01 = Error detected and message corrected 10 = Uncorrectable error 11 = No meaning
25:0	D[25:0]	EEPROM data

### MEMORY MAP

#### EEPROM/Shadow Memory

	Address	Bits																															
		31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
EEPROM	0x0B	ECC								IAVGSELEN	CRS_SNS		SNS_FINE						QVO_FINE														
	0x0C	ECC																RMS_AVG_2						RMS_AVG_1									
	0x0D	ECC				SQUAREWAVE_EN		HALFCYCLE_EN		FLTDLY			FAULT						CHAN_DEL_SEL		ICHAN_DEL_EN		PACC_TRIM										
	0x0E	ECC								DELAYCNT_SEL		UNDERVREG						OVERVREG						VADC_RATE_SET		VEVENT_CYCS							
	0x0F	ECC										DIO_1_SEL		DIO_0_SEL								I2C_DIS_SLV_ADDR		I2C_SLV_ADDR									
Shadow	0x1B									IAVGSELEN	CRS_SNS		SNS_FINE						QVO_FINE														
	0x1C																	RMS_AVG_2						RMS_AVG_1									
	0x1D					SQUAREWAVE_EN		HALFCYCLE_EN		FLTDLY			FAULT						UNUSED		CHAN_DEL_SEL		UNUSED		ICHAN_DEL_EN		PACC_TRIM						
	0x1E									DELAYCNT_SEL		UNDERVREG						OVERVREG						VADC_RATE_SET		VEVENT_CYCS							
	0x1F											DIO_1_SEL		DIO_0_SEL								I2C_DIS_SLV_ADDR		I2C_SLV_ADDR									

## Device Trim Flow

The trim process for voltage, current, and power channels are depicted in Figure 13 through Figure 15. Refer to the Register Details section for more information regarding trim fields.

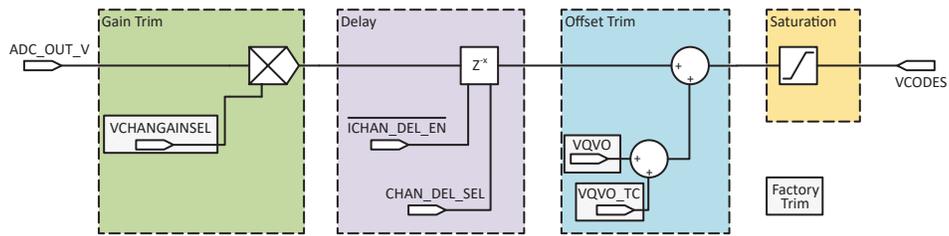


Figure 13: Voltage Channel Trim Flow

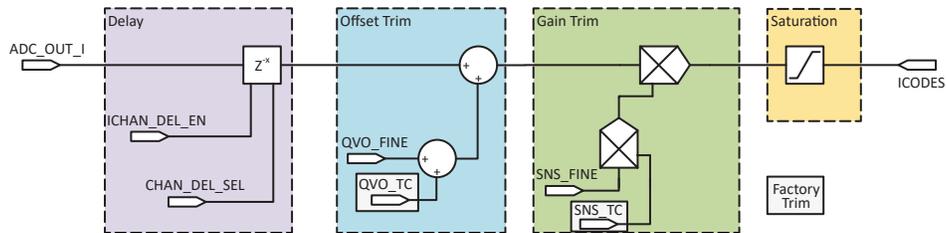


Figure 14: Current Channel Trim Flow

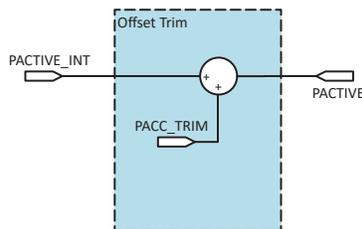


Figure 15: Power Channel Trim Flow

### Register Details – EEPROM

#### Register 0x0B/0x1B

Bits	Name	Default Value	Description
8:0	QVO_FINE	–	Offset fine trimming on current channel
17:9	SNS_FINE	–	Fine gain trimming on the current channel
20:18	CRS_SNS	–	Coarse gain setting
21	IAVGSELEN	–	Current Averaging selection
25:22	unused	–	Unused
31:26	ECC	–	Error Code Correction

#### QVO\_FINE

Offset adjustment for the current channel. This is a signed 9-bit number with an input range of –256 to 255. With a step size of 64 LSB, this equates to an offset trim range of –16384 to 16320 LSB, which is added to the icodes value. The trim is implemented as shown in Figure 14. The current channel’s offset trim should be applied before the gain is trimmed. QVO\_FINE is further described in Table 1.

Table 1: QVO\_FINE

Range	Value	Units
–256 to 255	–16,384 to 16,320	LSB

#### SNS\_FINE

Gain adjustment for the current channel. This is a signed 9-bit number with an input range of –256 to 255. This gain adjustment is implemented as a percentage multiplier centered around 1 (i.e. writing a 0 to this field multiplies the gain by 1, leaving the gain unaffected). The fine sensitivity parameter ranges from 50% to 150% of IP. The current channel’s offset trim should be applied before the gain is trimmed. SNS\_FINE is further described in Table 2.

Table 2: SNS\_FINE

Range	Value	Units
–256 to 255	50 to 100	%

#### CRS\_SNS

Coarse gain adjustment for the current channel. This gain is implemented in the analog domain before the ADC. This is a 3-bit number that allows for 8 gain selections. Adjustments to CRS\_SNS may impact the device’s performance over temperature. Datasheet limits apply only to the factory settings for CRS\_SNS. The gain settings map to 1×, 2×, 3×, 3.5×, 4×, 4.5×, 5.5×, and 8×. CRS\_SNS is further described in Table 3.

Table 3: CRS\_SNS

Range	Value	Units
0	1×	–
1	2×	–
2	3×	–
3	3.5×	–
4	4×	–
5	4.5×	–
6	5.5×	–
7	8×	–

#### IAVGSELEN

Current Averaging selection enable. 0 will select VRMS for averaging. 1 will select IRMS for averaging. See Figure 8.

### Register 0x0C/0x1C

Bits	Name	Default Value	Description
6:0	RMS_AVG_1	0	Average of the rms voltage or current – stage 1
16:7	RMS_AVG_2	0	Average of the rms voltage or current – stage 2
25:17	–	0	Reserved
31:26	ECC	–	Error Code Correction

### RMS\_AVG\_1

Number of averages for the first averaging stage (VRMSAVGONESEC or IRMSAVGONESEC). The value written into this field directly maps to the number of averages ranging from 0 to 127. For optimal performance, an even number of averages should be used. The channel to be averaged is selected by the current average select enable bit (IAVGSELEN). RMS\_AVG\_1 is further described in Table 4.

Table 4: RMS\_AVG\_1

Range	Value	Units
0 to 127	0 to 127	number of averages

### RMS\_AVG\_2

Number of averages for the second averaging stage (VRMSAVGONEMIN or IRMSAVGONEMIN). This stage averages the outputs of the first averaging stage. The value written into this field directly maps to the number of averages ranging from 0 to 1023. For optimal performance, an even number of averages should be used. The channel to be averaged is selected by the current average select enable bit (IAVGSELEN). RMS\_AVG\_2 is further described in Table 5.

Table 5: RMS\_AVG\_2

Range	Value	Units
0 to 1023	0 to 1023	number of averages

### Register 0x0D/0x1D

Bits	Name	Default Value	Description
6:0	PACC_TRIM	–	Trims the active power
7	ICHAN_DEL_EN	0	Enable phase delay on voltage or current channel
8	unused	0	unused
11:9	CHAN_DEL_SEL	0	Sets phase delay on voltage or current channel
12	unused	0	unused
20:13	FAULT	255	Sets the overcurrent fault threshold
23:21	FLTDLY	0	Sets the overcurrent fault delay
24	HALFCYCLE_EN	0	Outputs pulses at every zero crossing when enabled, and every rising edge when disabled
25	SQUAREWAVE_EN	0	Selects pulse or square wave output for the zero-crossing reporting
31:26	ECC	–	Error Code Correction

#### PACC\_TRIM

Offset trim in the active power calculation and is implemented as shown in Figure 15. This is a signed 7-bit number with an input range of –64 to 63. This equates to a trim range of –384 to 378 LSB, which is added to the PACTIVE value. PACC\_TRIM is further described in Table 6.

Table 6: PACC\_TRIM

Range	Value	Units
–64 to 63	–384 to 378	LSB

#### ICHAN\_DEL\_EN

Enables delay for either the voltage or current channel. Setting to 1 enables delay for the current channel. This behavior is depicted in Figure 13 and Figure 14. ICHAN\_DEL\_EN is further described in Table 7.

Table 7: ICHAN\_DEL\_EN

Range	Value	Units
0	0 – voltage channel	LSB
1	1 – current channel	LSB

#### CHAN\_DEL\_SEL

Sets the amount of delay applied to the voltage or current channel (set by ICHAN\_DEL\_EN). The step size of this field is determined by the value of VADC\_RATE\_SEL. CHAN\_DEL\_SEL is further described in Table 8.

Table 8: CHAN\_DEL\_SEL

VADC_RATE_SEL	Range	Value	Units
0	0 to 7	0 to 219	μs
1	0 to 7	0 to 875	μs

#### FAULT

Overcurrent fault threshold. This is an unsigned 8-bit number with an input range of 0 to 255, which equates to a fault range of 50% to 175% of IP. The factory setting of this field is 0. FAULT is further described in Table 9.

Table 9: FAULT

Range	Value	Units
0 to 255	50 to 175	% of IP

#### FLTDLY

Fault delay setting of the amount of delay applied before flagging a fault condition. FLTDLY is further described in Table 10.

Table 10: FLTDLY

Range	Value	Units
0	0	μs
1	0	μs
2	4.75	μs
3	9.25	μs
4	13.75	μs
5	18.5	μs
6	23.25	μs
7	27.75	μs

#### HALFCYCLE\_EN

Setting for the voltage zero-crossing detection. When set to 0, the voltage zero-crossing will be indicated on every rising edge. When set to 1, the voltage zero-crossing will be indicated on both rising and falling edges.

### SQUAREWAVE\_EN

Setting for the voltage zero-crossing detection. When set to 0, the zero-crossing event will be indicated by a pulse on the DIO pin. When set to 1, the zero-crossing event will be indicated by a level change on the DIO pin. Note that the device must be configured to report voltage-zero-crossing detection on the DIO pin.

### Register 0x0E/0x1E

Bits	Name	Default Value	Description
5:0	VEVENT_CYCS	0	Sets the number of qualifying cycles needed to flag overvoltage or undervoltage
6	VADC_RATE_SET	0	Sample Frequency Selection
7	–	0	Reserved
13:8	OVERVREG	32	Sets the overvoltage fault threshold
19:14	UNDERVREG	32	Sets the undervoltage fault threshold
20	DELAYCNT_SEL	0	Sets the width of the voltage zero-crossing output pulse
25:21	unused	0	Unused
31:26	ECC	–	Error Code Correction

#### VEVENT\_CYCS

Sets the number of cycles required to assert the OVRMS flag or the UVRMS. This is an unsigned 6-bit number with an input range of 0 to 63. The value in this field directly maps to the number of cycles. VEVENT\_CYCS is further described in Table 11.

Table 11: VEVENT\_CYCS

Range	Value	Units
0 to 63	1 to 64	cycles

#### VADC\_RATE\_SET

Sets the voltage ADC update rate. Setting this field to a 0 selects a 32 kHz update. Setting this field to a 1 selects a 4 kHz update, which will reduce the number of samples used in each rms calculation but will allow for a larger phase delay correction between channels (see CHAN\_DEL\_SEL). VADC\_RATE\_SET is further described in Table 12.

Table 12: VADC\_RATE\_SET

Range	Value	Units
0	32	kHz
1	4	kHz

#### OVERVREG

Sets the threshold of the overvoltage rms flag (OVRMS). This is a 6-bit number ranging from 0 to 63. This trip level spans the entire range of the VRMS register. The flag is set if the rms value is above this threshold for the number of cycles selected in VEVENT\_CYCS. OVERVREG is further described in Table 13.

Table 13: OVERVREG

Range	Value	Units
0 to 63	0 to 32,768	LSB

#### UNDERVREG

Sets the threshold of the undervoltage rms flag (UVRMS). This is a 6-bit number ranging from 0 to 63. This trip level spans one entire range of the VRMS register. The flag is set if the rms value is below this threshold for the number of cycles selected in VEVENT\_CYCS. UNDERVREG is further described in Table 14.

Table 14: UNDERVREG

Range	Value	Units
0 to 63	0 to 32,768	LSB

#### DELAYCNT\_SEL

Selection bit for the width of pulse for a voltage zero-crossing event. When set to 0, the pulse is 32  $\mu$ s. When set to 1, the pulse is 256  $\mu$ s. When the SQUAREWAVE\_EN bit is set, this field is ignored. DELAYCNT\_SEL is further described in Table 15.

Table 15: DELAYCNT\_SEL

Range	Value	Units
0	32	$\mu$ s
1	256	$\mu$ s

### Register 0x0F/0x1F

Bits	Name	Default Value	Description
1:0	unused	0	Unused
8:2	I2C_SLV_ADDR	0	I <sup>2</sup> C peripheral address selection
9	I2C_DIS_SLV_ADDR	0	Disable I <sup>2</sup> C peripheral address selection circuit
15:10	unused	0	Unused
17:16	DIO_0_SEL	0	Digital output 0 multiplexor selection bits
19:18	DIO_1_SEL	0	Digital output 1 multiplexor selection bits
25:20	unused	0	Unused
31:26	ECC	–	Error Code Correction

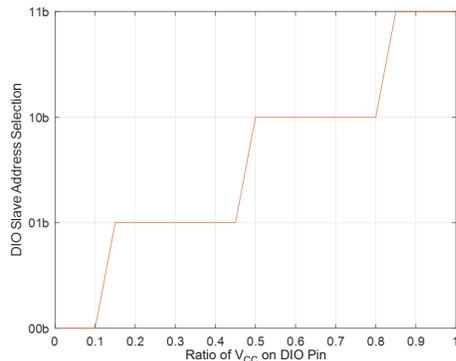
#### I2C\_SLV\_ADDR

Settings for the I<sup>2</sup>C peripheral address. The voltage on the DIO pins are measured at power and are used to set the device's peripheral address.

Each DIO pin has 4 voltage bins which may be used to set the I<sup>2</sup>C peripheral address. These voltages may be set using resistor divider circuits from V<sub>CC</sub> to ground. I2C\_SLV\_ADDR is further described in Table 16.

Table 16: I2C\_SLV\_ADDR

DIO_1 (decimal)	DIO_0 (decimal)	Peripheral Address (decimal)
0	0	96
0	1	97
0	2	98
0	3	99
1	0	100
1	1	101
1	2	102
1	3	103
2	0	104
2	1	105
2	2	106
2	3	107
3	0	108
3	1	109
3	2	110
3	3	EEPROM value



#### I2C\_DIS\_SLV\_ADDR

Enables or disables the analog I<sup>2</sup>C peripheral address feature at power on. When this bit is set, the I<sup>2</sup>C peripheral address will map directly to I2C\_SLV\_ADDR.

#### DIO\_0\_SEL

Determines which flags are output on the DIO0 pin. Only used when the device is in I<sup>2</sup>C programming mode. DIO\_0\_SEL is further described in Table 17.

Table 17: DIO\_0\_SEL

Value	Selection
0	VZC: Voltage zero crossing
1	OVRMS: The VRMS overvoltage flag
2	UVRMS: The VRMS undervoltage flag
3	The OR of OVRMS and UVRMS (if either flag is triggered, the DIO_0 pin will be asserted)

#### DIO\_1\_SEL

Determines which flags are output on the DIO1 pin. Only used when the device is in I<sup>2</sup>C programming mode. DIO\_1\_SEL is further described in Table 18.

Table 18: DIO\_1\_SEL

Value	Selection
0	OCF: Overcurrent fault
1	UVRMS: The VRMS undervoltage flag
2	OVRMS: The VRMS overvoltage flag
3	The OR of OVRMS, UVRMS, and OCF (if any of the three flags are triggered, the DIO_0 pin will be asserted).

# ACS71020

## Single Phase, Isolated, AC Power Monitoring IC with Voltage Zero Crossing and Overcurrent Detection

### Volatile Memory

Address	Bits																															
	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0x20	IRMS																VRMS															
0x21	PACTIVE																															
0x22	PAPPARENT																															
0x23	PIMAG																															
0x24																	PFACTOR															
0x25																	NUMPTSOUT															
0x26	IRMSAVGONESEC																VRMSAVGONESEC															
0x27	IRMSAVGONEMIN																VRMSAVGONEMIN															
0x28																	PACTAVGONESEC															
0x29																	PACTAVGONEMIN															
0x2A																	VCODES															
0x2B																	ICODES															
0x2C	PINSTANT																															
0x2D																	POSPF POSANGLE UNDERVOLTAGE OVERVOLTAGE FAULTLATCHED FAULTOUT VZEROCROSSOUT															
0x2E																																
0x2F	ACCESS_CODE																															
0x30																																CUSTOMER_ACCESS
0x31																																

VOLATILE

### Register Details – Volatile

#### Register 0x20

Bits	Name	Description
14:0	VRMS	Voltage rms value
30:16	IRMS	Current rms value

#### VRMS

RMS voltage output. This field is an unsigned 15-bit fixed point number with 15 fractional bits. It ranges from 0 to  $\sim 1$  with a step size of  $1/2^{15}$ . This number should be multiplied by the overall full scale of the voltage path in order to get to volts. For example, the device is trimmed to a full scale input of 275 mV, and if a resistor divider network is used to create 275 mV when it has 250 V across it, then the multiplier should be 250 V. VRMS is further described in Table 19.

Table 19: VRMS

Range	Value	Units
0 to $\sim 1$	$[0 \text{ to } \sim 1] \times \Delta V_{IN(MAX)}$	V

#### IRMS

RMS current output. This field is an unsigned 15-bit fixed point number with 14 fractional bits. It ranges from 0 to  $\sim 2$  with a step size of  $1/2^{14}$ . This number should be multiplied by the overall full scale of the current path in order to get to amps. For example, if the device is trimmed to a full-scale input of 30 A, then the multiplier should be 30 A. IRMS is further described in Table 20.

Table 20: IRMS

Range	Value	Units
0 to $\sim 2$	$[0 \text{ to } \sim 2] \times I_{PR(MAX)}$	A

#### Register 0x21

Bits	Name	Description
16:0	PACTIVE	Active power

#### PACTIVE

Active power output. This field is a signed 17-bit fixed point number with 15 fractional bits. It ranges from  $\sim 2$  to  $\sim 2$  with a step size of  $1/2^{15}$ . This number should be multiplied by the overall full-scale power in order to get to watts. For example, if full-scale voltage is 250 V and  $I_{PR}$  is 30 A, the multiplier will be 7500 W. PACTIVE is further described in Table 21.

Table 21: PACTIVE

Range	Value	Units
$\sim 2$ to $\sim 2$	$[-2 \text{ to } \sim 2] \times \text{MaxPow}$	W

### Register 0x22

Bits	Name	Description
15:0	PAPPARENT	Apparent power

#### PAPPARENT

Apparent power output. This field is an unsigned 16-bit fixed point number with 15 fractional bits. It ranges from 0 to  $\sim 2$  with a step size of  $1/2^{15}$ . This number should be multiplied by the overall full-scale power in order to get to VA. For example, if full scale voltage is 250 V and  $I_{PR}$  is 30 A, then the multiplier will be 7500 VA. PAPPARENT is further described in Table 22.

Table 22: PAPPARENT

Range	Value	Units
0 to $\sim 2$	$[0 \text{ to } \sim 2] \times \text{MaxPow}$	VA

### Register 0x23

Bits	Name	Description
15:0	PIMAG	Reactive power

#### PIMAG

Reactive power output. This field is an unsigned 16-bit fixed point number with 15 fractional bits. It ranges from 0 to  $\sim 2$  with a step size of  $1/2^{15}$ . This number should be multiplied by the overall full-scale power in order to get to VAR. For example, if full-scale voltage is 250 V and  $I_{PR}$  is 30 A, then the multiplier will be 7500 VAR. PIMAG is further described in Table 23.

Table 23: PIMAG

Range	Value	Units
0 to $\sim 2$	$[0 \text{ to } \sim 2] \times \text{MaxPow}$	VAR

### Register 0x24

Bits	Name	Description
10:0	PFACTOR	Power factor

### PFACTOR

Power factor output. This field is a signed 11-bit fixed point number with 9 fractional bits. It ranges from  $-2$  to  $\sim 2$  with a step size of  $1/2^9$ . PFACTOR is further described in Table 24.

Table 24: PFACTOR

Range	Value	Units
$-2$ to $\sim 2$	$-2$ to $\sim 2$	–

### Register 0x25

Bits	Name	Description
8:0	NUMPTSOUT	Number of samples of current and voltage used for calculations

### NUMPTSOUT

Number of points used in the rms calculation. This will be the dynamic value that is evaluated internal to the device based on zero crossings of the voltage channel. NUMPTSOUT is further described in Table 25.

Table 25: NUMPTSOUT

Range	Value	Units
0 to 511	0 to 511	–

### Register 0x26

Bits	Name	Description
14:0	VRMSAVGONESEC	Averaged voltage rms value. Duration set by RMS_AVG_1. This register will be zero if IAVGSELEN = 1.
30:16	IRMSAVGONESEC	Averaged current rms value. Duration set by RMS_AVG_1. This register will be zero if IAVGSELEN = 0.

#### VRMSAVGONESEC

Voltage rms value averaged according to RMS\_AVG\_1. This register will be zero if IAVGSELEN = 1.

#### IRMSAVGONESEC

Current rms value averaged according to RMS\_AVG\_1. This register will be zero if IAVGSELEN = 0.

### Register 0x27

Bits	Name	Description
14:0	VRMSAVGONEMIN	Averaged voltage rms value. Duration set by RMS_AVG_2. This register will be zero if IAVGSELEN = 1.
30:16	IRMSAVGONEMIN	Averaged current rms value. Duration set by RMS_AVG_2. This register will be zero if IAVGSELEN = 0.

#### VRMSAVGONEMIN

Voltage rms value averaged according to RMS\_AVG\_2. This register will be zero if IAVGSELEN = 1.

#### IRMSAVGONEMIN

Current rms value averaged according to RMS\_AVG\_2. This register will be zero if IAVGSELEN = 0.

### Register 0x28

Bits	Name	Description
16:0	PACTAVGONESEC	Active power value averaged over up to one second. Duration set by RMS_AVG_1.

#### PACTAVGONESEC

Active power value averaged according to RMS\_AVG\_1.

### Register 0x29

Bits	Name	Description
16:0	PACTAVGONEMIN	Active Power value averaged over up to one minute. Duration set by RMS_AVG_2.

#### PACTAVGONEMIN

Active power value averaged according to RMS\_AVG\_2.

### Register 0x2A

Bits	Name	Description
16:0	VCODES	Instantaneous voltage measurement

#### VCODES

This field contains the instantaneous voltage measurement before any rms calculations are done. It is a 17-bit signed fixed-point number with 16 fractional bits. It ranges from  $-1$  to  $\sim 1$  with a step size of  $1/2^{16}$ . This number should be multiplied by the overall full scale of the voltage path in order to get volts. For example, the device is trimmed to a full-scale input of 275 mV, and if a resistor divider network is used to create 275 mV, when it has 250 V across it, then the multiplier should be 250 V. VCODES is further described in Table 26.

Table 26: VCODES

Range	Value	Units
$-1$ to $\sim 1$	$[-1 \text{ to } \sim 1] \times \Delta V_{IN(MAX)}$	V

### Register 0x2B

Bits	Name	Description
16:0	ICODES	Instantaneous current measurement

#### ICODES

This field contains the instantaneous current measurement before any rms calculations are done. This field is a signed 17-bit fixed point number with 15 fractional bits. It ranges from  $-2$  to  $\sim 2$  with a step size of  $1/2^{15}$ . This number should be multiplied by the overall full scale of the current path in order to get amps. For example, the device is trimmed to a full-scale input of 30 A, then the multiplier should be 30 A. ICODES is further described in Table 27.

Table 27: ICODES

Range	Value	Units
$-2$ to $\sim 2$	$[-2 \text{ to } \sim 2] \times I_{PR(MAX)}$	A

### Register 0x2C

Bits	Name	Description
31:0	PINSTANT	Instantaneous power; multiplication of VCODES and ICODES

### PINSTANT

This field contains the instantaneous power measurement before any rms calculations are done. This field is a signed 32-bit fixed point number with 29 fractional bits. It ranges from  $-4$  to  $\sim 4$  with a step size of  $1/2^{29}$ . This number should be multiplied by the overall full-scale power in order to get to watts. For example, if full scale voltage is 250 V and  $I_{PR}$  is 30 A, then the multiplier will be 7500 W. PINSTANT is further described in Table 28.

Table 28: PINSTANT

Range	Value	Units
$-4$ to $\sim 4$	$[-4$ to $\sim 4] \times \text{MaxPow}$	W

### Register 0x2D

Bits	Name	Description
0	VZEROCROSSOUT	Voltage zero-crossing output
1	FAULTOUT	Current fault output
2	FAULTLATCHED	Current fault output latched
3	OVERVOLTAGE	Overvoltage flag
4	UNDERVOLTAGE	Undervoltage flag
5	POSANGLE	Sign of the power angle
6	POSPF	Sign of the power factor

### VZEROCROSSOUT

Flag for the voltage zero-crossing events. Will be present and active regardless of DIO\_0\_SEL and DIO\_1\_SEL. This flag will still follow the HALFCYCLE\_EN and SQUAREWAVE\_EN settings.

### FAULTOUT

Flag for the overcurrent events. Will be present and active regardless of DIO\_0\_SEL and DIO\_1\_SEL. Will only be set when fault is present.

### FAULTLATCHED

Flag for the overcurrent events. This bit will latch and will remain 1 as soon as an overcurrent event is detected. This can be reset by writing a 1 to this field. Will be present and active regardless of DIO settings.

### OVERVOLTAGE

Flag for the overvoltage events. Will be present and active regardless of DIO\_0\_SEL and DIO\_1\_SEL. Will only be set when fault is present.

### UNDERVOLTAGE

Flag for the undervoltage events. Will be present and active regardless of DIO\_0\_SEL and DIO\_1\_SEL. Will only be set when fault is present.

### POSANGLE

Bit to represent leading or lagging. A 0 represents the current leading and a 1 represents the current lagging.

### POSPF

Sign bit to represent if the power is being generated (0) or consumed (1).

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# ACS71020

## Single Phase, Isolated, AC Power Monitoring IC with Voltage Zero Crossing and Overcurrent Detection

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### Register 0x2F

Bits	Name	Description
31:0	ACCESS_CODE	Access code register: Customer code: 0x4F70656E

### Register 0x30

Bits	Name	Description
0	CUSTOMER_ACCESS	Customer write access enabled. 0 = Non-customer mode. 1 = Customer mode.

### VOLTAGE INPUT APPLICATION CONNECTIONS

Due to the input buffer common-mode input voltage requirement, there are possible two circuit configurations:

1. In Figure 16: the neutral line must be isolated from the ground powering the device to allow the common mode voltage of  $V_{INN}$  to sit at  $2/3 V_{CC}$ .
2. In Figure 17: capacitors block the DC component of the voltage input and allow the internal resistor divider to bias

$V_{INN}$  to  $2/3 V_{CC}$ . If the isolation state of the application is unknown, this schematic works in both cases.

$R_{SENSE}$  should be sized according to the full-scale signal level that can be applied to the voltage channel  $\pm 275$  mV and expected maximum measured voltage.

$R_{SENSE}$  values used in figures below are examples for AC 240 Vrms input signal.

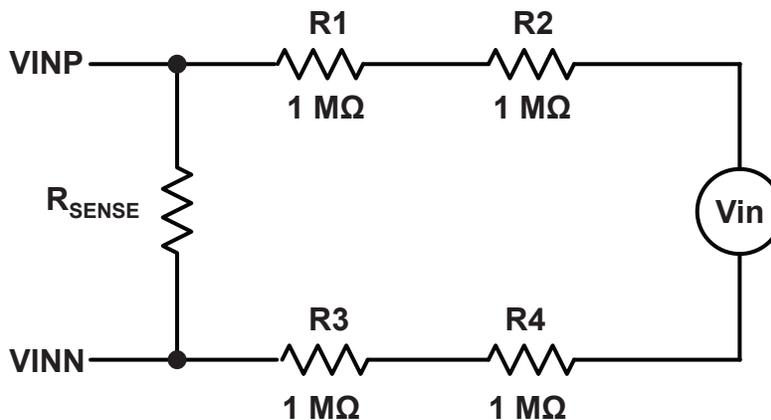


Figure 16: Floating AC voltage source (device ground is isolated)

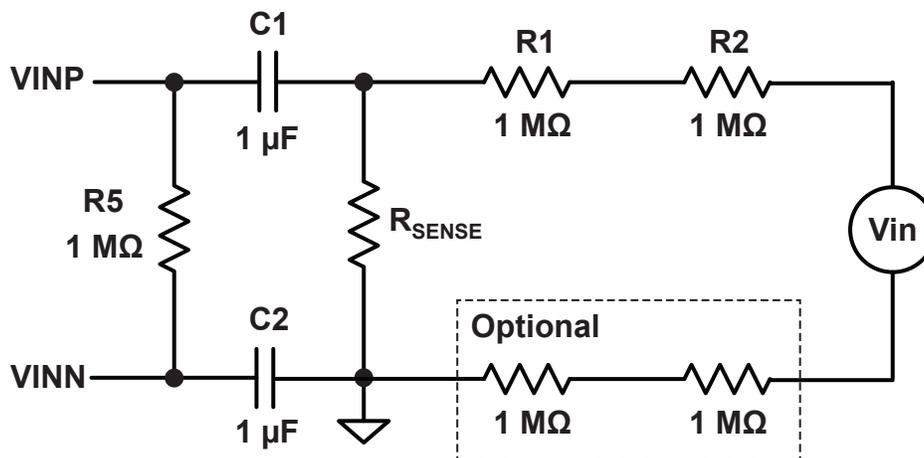


Figure 17: Ground referenced AC voltage source (device GND is common with voltage source GND)

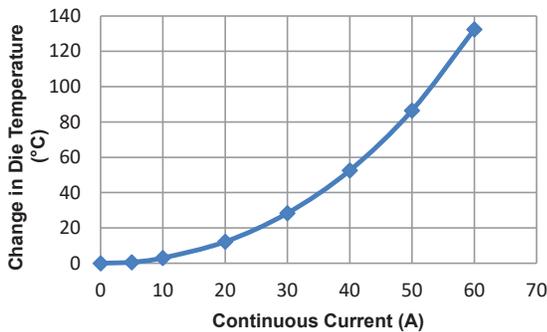
## APPLICATION INFORMATION

### Thermal Rise vs. Primary Current

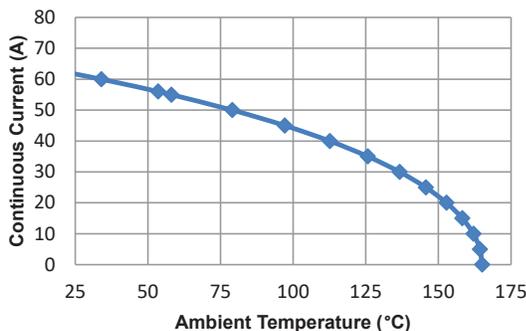
Self-heating due to the flow of current should be considered during the design of any current sensing system. The sensor, printed circuit board (PCB), and contacts to the PCB will generate heat as current moves through the system.

The thermal response is highly dependent on PCB layout, copper thickness, cooling techniques, and the profile of the injected current. The current profile includes peak current, current on-time, and duty cycle. While the data presented in this section was collected with direct current (DC), these numbers may be used to approximate thermal response for both AC signals and current pulses.

The plot in Figure 18 shows the measured rise in steady-state die temperature of the ACS71020 versus continuous current at an ambient temperature,  $T_A$ , of 25 °C. The thermal offset curves may be directly applied to other values of  $T_A$ . Conversely, Figure 19 shows the maximum continuous current at a given  $T_A$ . Surges beyond the maximum current listed in Figure 19 are allowed given the maximum junction temperature,  $T_{J(MAX)}$  (165°C), is not exceeded.



**Figure 18: Self Heating in the MA Package Due to Current Flow**

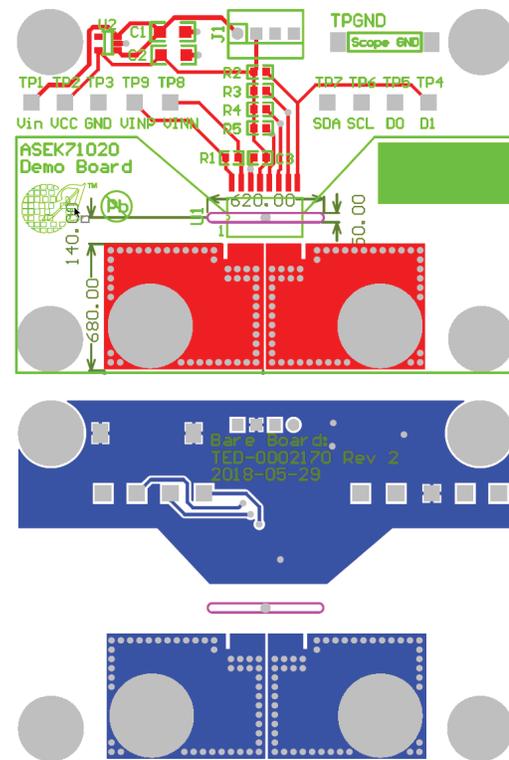


**Figure 19: Maximum Continuous Current at a Given  $T_A$**

The thermal capacity of the ACS71020 should be verified by the end user in the application's specific conditions. The maximum junction temperature,  $T_{J(MAX)}$  (165°C), should not be exceeded. Further information on this application testing is available in the [DC and Transient Current Capability application note](#) on the Allegro website.

### ASEK71020 Evaluation Board Layout

Thermal data shown in Figure 18 and Figure 19 was collected using the ASEK71020 Evaluation Board (TED-0002170). This board includes 1500 mm<sup>2</sup> of 2 oz. copper (0.0694 mm) connected to pins 1 through 4, and to pins 5 through 8, with thermal vias connecting the layers. Top and Bottom layers of the PCB are shown below in Figure 20.



**Figure 20: Top and Bottom Layers for ASEK71020 Evaluation Board**



## PACKAGE OUTLINE DRAWING

### For Reference Only – Not for Tooling Use

(Reference Allegro DWG-0000388, Rev. 1 and JEDEC MS-013AA)

NOT TO SCALE

Dimensions in millimeters

Dimensions exclusive of mold flash, gate burrs, and dambar protrusions  
Exact case and lead configuration at supplier discretion within limits shown

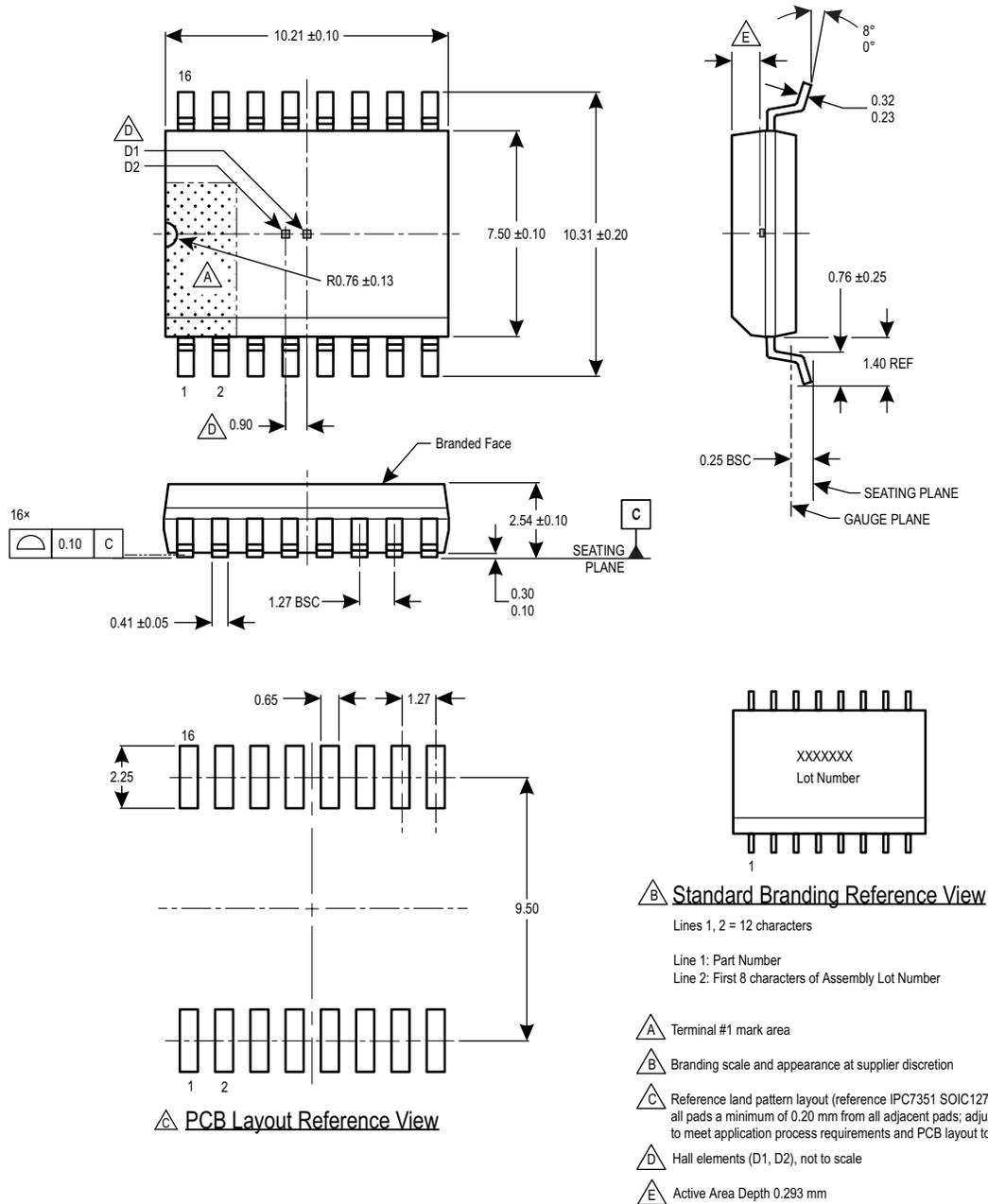


Figure 22: Package MA, 16-Pin SOICW

### Revision History

Number	Date	Description
–	June 20, 2018	Initial release
1	September 19, 2018	Updated Features and Benefits, Description (page 1), Isolation Characteristics, Thermal Characteristics (page 3), Power Calculations section (pages 13-14), Digital Communication (page 15), Register Details (pages 20-33), Applications Connections (page 34), and Package Outline Drawing (page 36).
2	December 14, 2018	Updated certification
3	January 10, 2019	Updated register defaults (pages 20-22, 24-25), Voltage Input Application Connections section (page 34), bypass_n_en description (page 24), and pfactor description (page 29).
4	March 15, 2019	Updated Title (all pages), Voltage Zero Crossing (page 6), ADCs section (page 12), Communication Interfaces section (page 15), Memory Map (page 18), Register 0x0C/0x1C (page 21), Register 0x0E/0x1E (page 24), Register 0x25 (page 29), and Application Connections (page 34). Added Operating Characteristics footnote (page 8).
5	April 29, 2019	Updated Figure 1 (page 1), Power Calculations section (page 14-16), Register 0x0C/0x1C (page 23), Table 16 (page 27), Volatile Memory table (page 28), Register 28 (page 30), Register 0x2C (page 34), and Figure 17 (page 36); added Power-On Time (page 6) and DIO Pins characteristics (page 7).
6	May 15, 2019	Updated Creepage (page 3); added TUV certificate mark.
7	June 3, 2019	Updated Table 12 (page 26), register 0x28, and register 0x29 (page 32).
8	June 17, 2019	Updated posangle and pospf (page 34).
9	November 21, 2019	Added Maximum Continuous Current to Absolute Maximum Ratings table, Distance Through Insulation and Comparative Tracking Index to Isolation Characteristics table, ESD ratings table (page 3), and thermal data section (page 37)
10	December 17, 2021	Updated package drawing (page 39) and minor editorial updates
11	January 3, 2024	Fixed broken link (pages 3, 37)
12	January 23, 2025	Updated registers to current standard (uppercase) and minor editorial updates
	March 27, 2025	Updated product status to not for new design (cover sheet), and removed reference to availability of evaluation board Gerber files on website (page 37)

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